LOW SKEW, 1-to-4 LVCMOS/LVTTL-TO-3.3V LVPECL FANOUT BUFFER

ICS8535BI-01

GENERAL DESCRIPTION

ICS HiPerClockS™

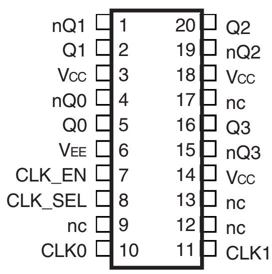
The ICS8535BI-01 is a low skew, high performance 1-to-4 LVCMOS/LVTTL-to-3.3V LVPECL fanout buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from IDT. The ICS8535BI-01 has two single ended clock inputs. the single ended clock input accepts LVCMOS or LVTTL input levels and translate them to 3.3V LVPECL levels. The clock enable is internally synchronized to eliminate runt clock pulses on the output during asynchronous assertion/deassertion of the clock enable pin.

Guaranteed output and part-to-part skew characteristics make the ICS8535BI-01 ideal for those applications demanding well defined performance and repeatability.

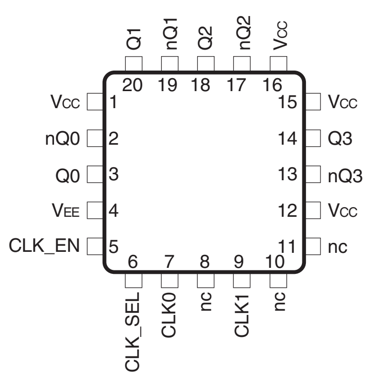
FEATURES

- Four differential 3.3V LVPECL outputs
- Selectable CLK0 or CLK1 inputs for redundant and multiple frequency fanout applications
- CLK0 or CLK1 can accept the following input levels: LVCMOS or LVTTL
- Maximum output frequency: 266MHz
- Translates LVCMOS and LVTTL levels to 3.3V LVPECL levels
- Output skew: TBD
- Part-to-part skew: TBD
- Propagation delay: 1.3ns (typical)
- Additive phase jitter, RMS: 0.04ps (typical)
- 3.3V operating supply
- -40°C to 85°C ambient operating temperature
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages

PIN ASSIGNMENT

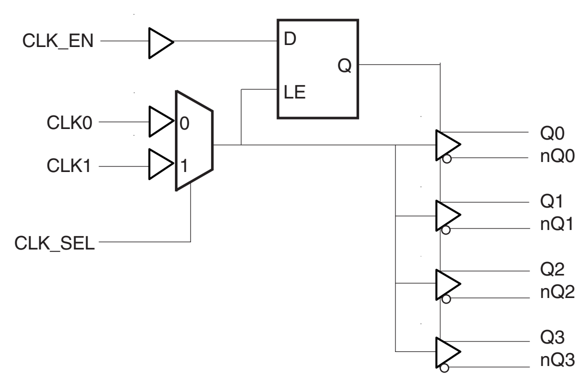


ICS8535BI-01
20-Lead TSSOP
4.4mm x 6.5mm x 0.925mm body package
G Package
Top View



ICS8535BI-01
20-Lead VFQFN
4mm x 4mm x 0.925mm body package
K Package
Top View

BLOCK DIAGRAM



The Preliminary Information presented herein represents a product in pre-production. The noted characteristics are based on initial product characterization and/or qualification. Integrated Device Technology, Incorporated (IDT) reserves the right to change any circuitry or specifications without notice.

TABLE 1. PIN DESCRIPTIONS

Name	Type		Description
V_{EE}	Power		Negative supply pin.
CLK_EN	Input	Pullup	Synchronizing clock enable. When HIGH, clock outputs follow clock input. When LOW, Q outputs are forced low, nQ outputs are forced high. LVCMOS / LVTTL interface levels.
CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects CLK1 input. When LOW, selects CLK0 input. LVCMOS / LVTTL interface levels.
CLK0	Input	Pulldown	LVCMOS / LVTTL clock input.
CLK1	Input	Pulldown	LVCMOS / LVTTL clock input.
nc	Unused		No connect.
V_{CC}	Power		Positive supply pins.
nQ3, Q3	Output		Differential output pair. LVPECL interface levels.
nQ2, Q2	Output		Differential output pair. LVPECL interface levels.
nQ1, Q1	Output		Differential output pair. LVPECL interface levels.
nQ0, Q0	Output		Differential output pair. LVPECL interface levels.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF
R_{PULLUP}	Input Pullup Resistor			51		kΩ
$R_{PULLDOWN}$	Input Pulldown Resistor			51		kΩ

TABLE 3A. CONTROL INPUT FUNCTION TABLE

Inputs			Outputs	
CLK_EN	CLK_SEL	Selected Source	Q0:Q3	nQ0:nQ3
0	0	CLK0	Disabled; LOW	Disabled; HIGH
0	1	CLK1	Disabled; LOW	Disabled; HIGH
1	0	CLK0	Enabled	Enabled
1	1	CLK1	Enabled	Enabled

After CLK_EN switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as show in Figure 1.
In the active mode, the state of the outputs are a function of the CLK0 and CLK1 inputs as described in Table 3B.

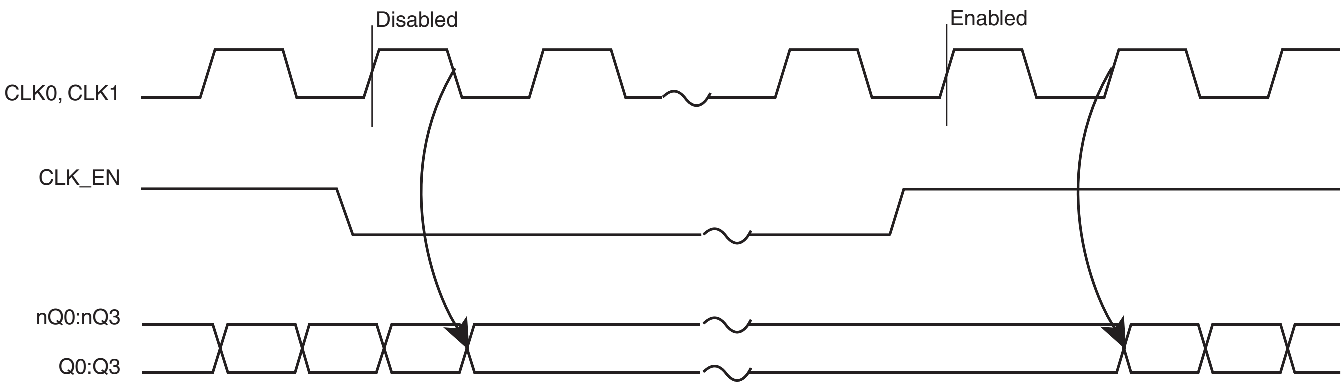


FIGURE 1. CLK_EN TIMING DIAGRAM

TABLE 3B. CLOCK INPUT FUNCTION TABLE

Inputs	Outputs	
CLK0 or CLK1	Q0:Q3	nQ0:nQ3
0	LOW	HIGH
1	HIGH	LOW

Absolute Maximum Ratings

Supply Voltage, V_{CC}	4.6V
Inputs, V_I	-0.5V to V_{CC} + 0.5V
Outputs, I_O	
Continuous Current	50mA
Surge Current	100mA
Package Thermal Impedance, θ_{JA}	
20 Lead TSSOP	91.1°C/W (0 mps)
20 Lead VFQFN	57.5°C/W (0 mps)
Storage Temperature, T_{STG}	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics, V_{CC} = 3.3V±5%, V_{EE} = 0V, TA = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Positive Supply Voltage		3.135	3.3	3.465	V
I_{EE}	Power Supply Current			45		mA

Table 4B. LVCMOS / LVTTL DC Characteristics, V_{CC} = 3.3V±5%, V_{EE} = 0V, TA = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage	CLK0, CLK1		2		V_{CC} + 0.3	V
		CLK_EN, CLK_SEL		2		V_{CC} + 0.3	V
V_{IL}	Input Low Voltage	CLK0, CLK1		-0.3		1.3	V
		CLK_EN, CLK_SEL		-0.3		0.8	V
I_{IH}	Input High Current	CLK0, CLK1, CLK_SEL	V_{IN} = V_{CC} = 3.465V			150	µA
		CLK_EN	V_{IN} = V_{CC} = 3.465V			5	µA
I_{IL}	Input Low Current	CLK0, CLK1, CLK_SEL	V_{IN} = 0V, V_{CC} = 3.465V	-5			µA
		CLK_EN	V_{IN} = 0V, V_{CC} = 3.465V	-150			µA

Table 4C. LVPECL DC Characteristics, V_{CC} = 3.3V±5%, V_{EE} = 0V, TA = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Voltage; NOTE 1		V_{CC} - 1.4		V_{CC} - 0.9	V
V_{OL}	Output Low Voltage; NOTE 1		V_{CC} - 2.0		V_{CC} - 1.7	V
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with 50Ω to V_{CC} - 2V.

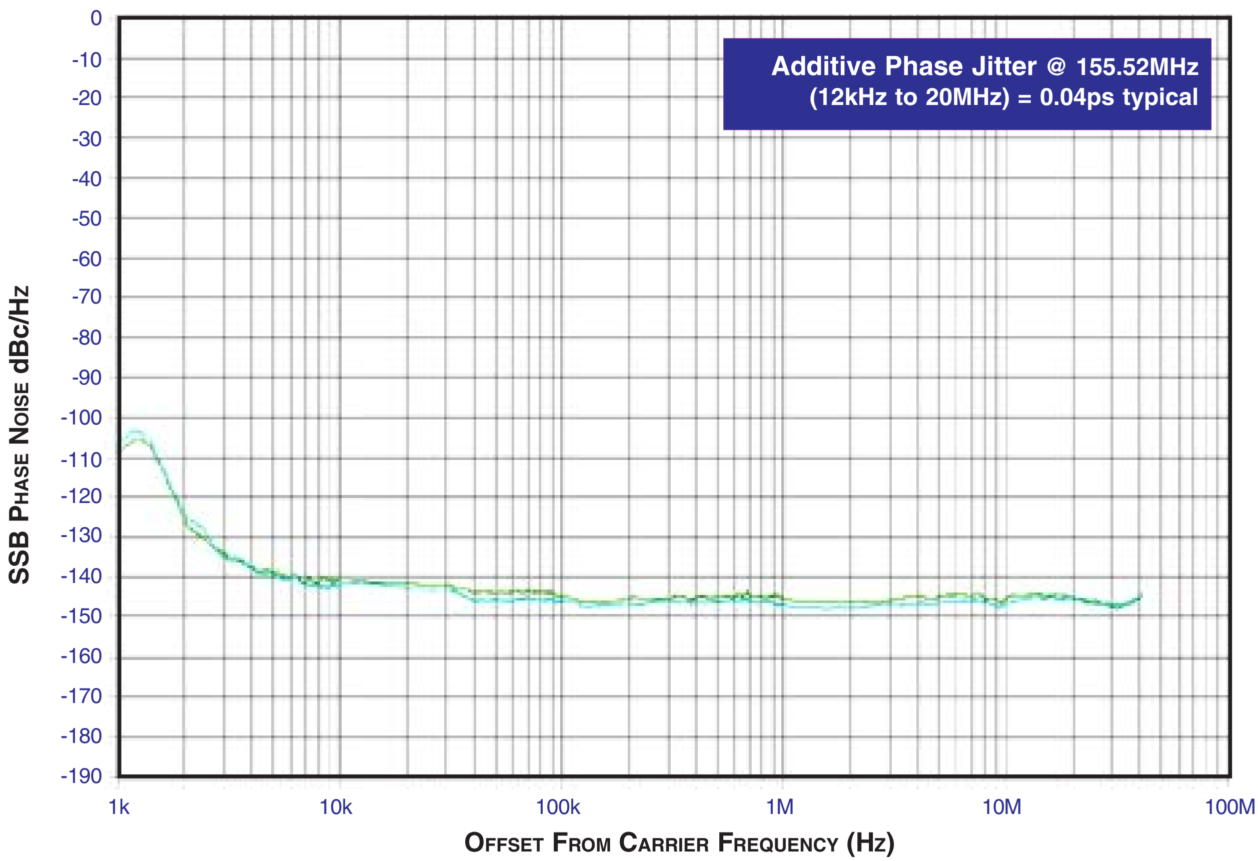
TABLE 5. AC CHARACTERISTICS, V_{CC} = 3.3V±5%, V_{EE} = 0V, TA = -40°C TO 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency				266	MHz
t_{PD}	Propagation Delay; NOTE 1			1.3		ns
*t*sk(o)	Output Skew; NOTE 2, 4			TBD		ps
*t*sk(pp)	Part-to-Part Skew; NOTE 3, 4			TBD		ps
*t*jit	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter section	*ƒ* = 155.52MHz (Integration Range: 12kHz - 20MHz)		0.04		ps
t_R / t_F	Output Rise/Fall Time	20% to 80% @ 50MHz		450		ps
odc	Output Duty Cycle			50		%

All parameters measured at 266MHz unless noted otherwise.
The cycle-to-cycle jitter on the input will equal the jitter on the output. The part does not add jitter.
NOTE 1: Measured from the $V_{CC}/2$ of the input to the differential output crossing point.
NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.
Measured at the output differential cross points.
NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.
NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

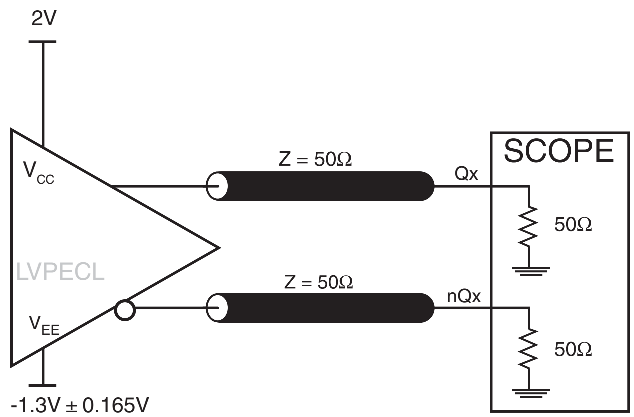
Additive Phase Jitter

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the ***dBc Phase Noise.*** This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a ***dBc*** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.

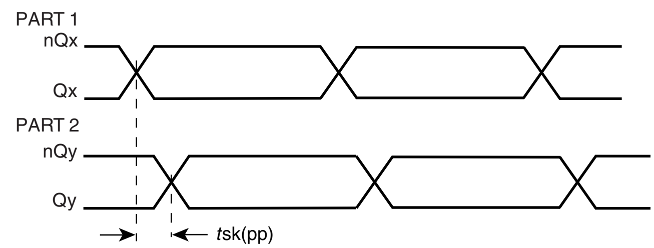


As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependant on the input source and measurement equipment.

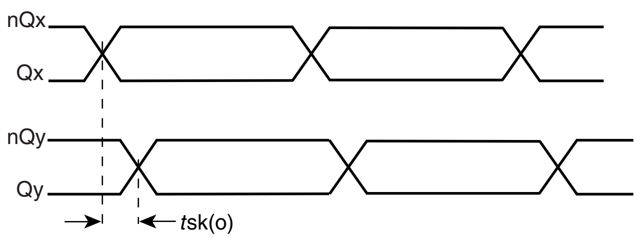
PARAMETER MEASUREMENT INFORMATION



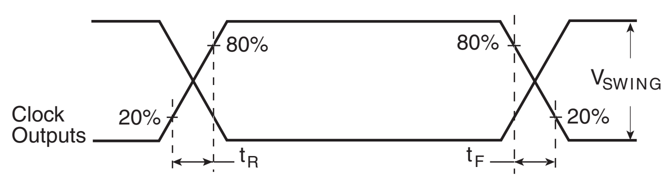
3.3V OUTPUT LOAD AC TEST CIRCUIT



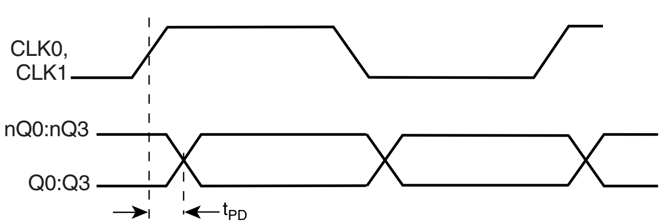
PART-TO-PART SKEW



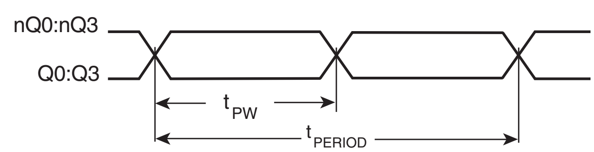
OUTPUT SKEW



OUTPUT RISE/FALL TIME



PROPAGATION DELAY



$$odc = \frac{t_{PW}}{t_{PERIOD}} \times 100\%$$

OUTPUT DUTY CYCLE/ PULSE WIDTH/PERIOD

APPLICATION INFORMATION

RECOMMENDATIONS FOR UNUSED INPUT AND OUTPUT PINS

INPUTS:

CLK INPUTS
For applications not requiring the use of a clock input, it can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from the CLK input to ground.

LVCMOS CONTROL PINS
All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

OUTPUTS:

LVPECL OUTPUTS
All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

TERMINATION FOR LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 2A and 2B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

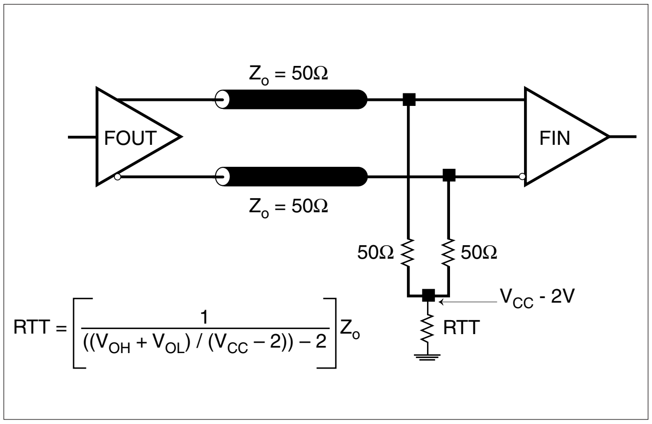


FIGURE 2A. LVPECL OUTPUT TERMINATION

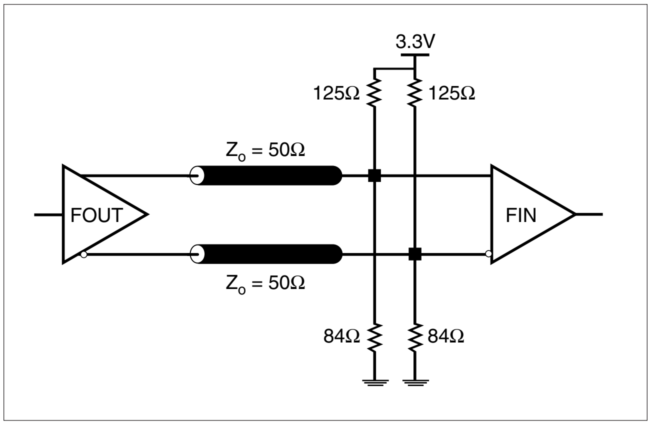


FIGURE 2B. LVPECL OUTPUT TERMINATION

VFQFN EPAD Thermal Release Path

In order to maximize both the removal of heat from the package and the electrical performance, a land pattern must be incorporated on the Printed Circuit Board (PCB) within the footprint of the package corresponding to the exposed metal pad or exposed heat slug on the package, as shown in *Figure 3.* The solderable area on the PCB, as defined by the solder mask, should be at least the same size/shape as the exposed pad/slug area on the package to maximize the thermal/electrical performance. Sufficient clearance should be designed on the PCB between the outer edges of the land pattern and the inner edges of pad pattern for the leads to avoid any shorts.

While the land pattern on the PCB provides a means of heat transfer and electrical grounding from the package to the board through a solder joint, thermal vias are necessary to effectively conduct from the surface of the PCB to the ground plane(s). The land pattern must be connected to ground through these vias. The vias act as “heat pipes”. The number of vias (i.e. “heat pipes”) are application specific and dependent upon the package power dissipation as well as electrical conductivity requirements. Thus, thermal and electrical analysis and/or testing are recommended to determine the minimum number needed. Maximum thermal and electrical performance is achieved when an array of vias is incorporated in the land pattern. It is recommended to use as many vias connected to ground as possible. It is also recommended that the via diameter should be 12 to 13mils (0.30 to 0.33mm) with 1oz copper via barrel plating. This is desirable to avoid any solder wicking inside the via during the soldering process which may result in voids in solder between the exposed pad/ slug and the thermal land. Precautions should be taken to eliminate any solder voids between the exposed heat slug and the land pattern. Note: These recommendations are to be used as a guideline only. For further information, refer to the Application Note on the *Surface Mount Assembly* of Amkor’s Thermally/ Electrically Enhance Leadfame Base Package, Amkor Technology.

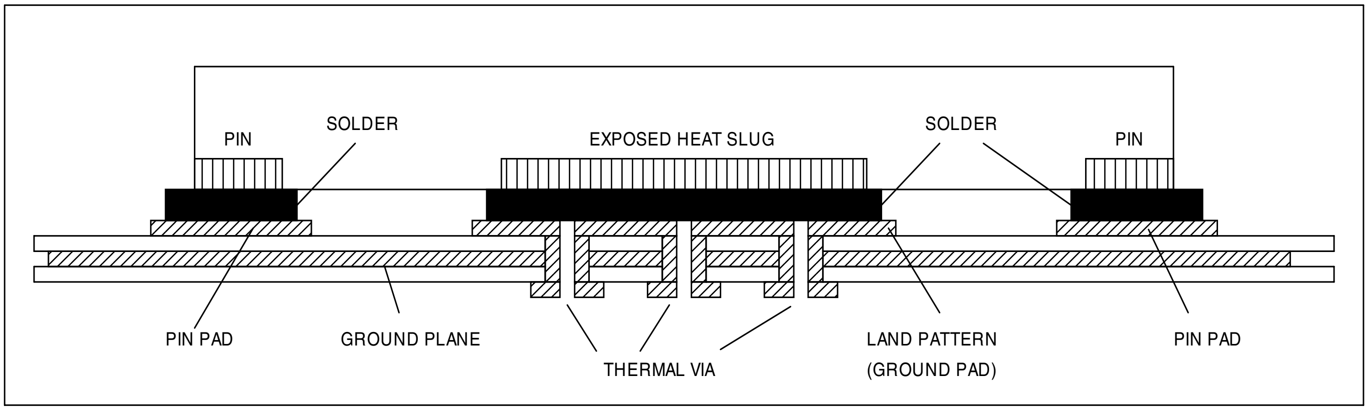


Figure 3. P.C.Assembly for Exposed Pad Thermal Release Path –Side View (Drawing not to Scale)

Power Considerations

This section provides information on power dissipation and junction temperature for the ICS8535BI-01.
Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS8535BI-01 is the sum of the core power plus the power dissipated in the load(s).
The following is the power dissipation for V_{CC} = 3.3V + 5% = 3.465V, which gives worst case results.
NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power $(core)_{MAX} = V_{CC\_MAX} * I_{EE\_MAX}$ = 3.465V * 45mA = **155.9mW**
- Power $(outputs)_{MAX}$ = **30mW/Loaded Output pair**
  If all outputs are loaded, the total power is 4 x 30mW = **120mW**

Total Power $_{\_MAX}$ (3.465V, with all outputs switching) = 155.9mW + 120mW = **275.9mW**

2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for Tj is as follows: $Tj = \theta_{JA} * Pd\_total + T_A$

Tj = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air low of 200 linear feet per minute and a multi-layer board, the appropriate value is 91.1°C/W per Table 6A below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:
85°C + 0.276W * 91.1°C/W = 110.1°C. This is well below the limit of 125°C.

This calculation is only an example, and the Tj will obviously vary depending on the number of outputs that are loaded, supply voltage, air flow, and the type of board (single layer or multi-layer).

Table 6A. Thermal Resistance θ_{JA} for 20-Lead TSSOP, Forced Convection

θ_{JA} by Velocity (Meters per Second)			
	0	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	91.1°C/W	86.7°C/W	84.6°C/W

Table 6B. θ_{JA} vs. Air Flow Table for 20 Lead VFQFN

θ_{JA} by Velocity (Meters per Second)			
	0	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	57.5°C/W	50.3°C/W	45.1°C/W

3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in *Figure 4.*

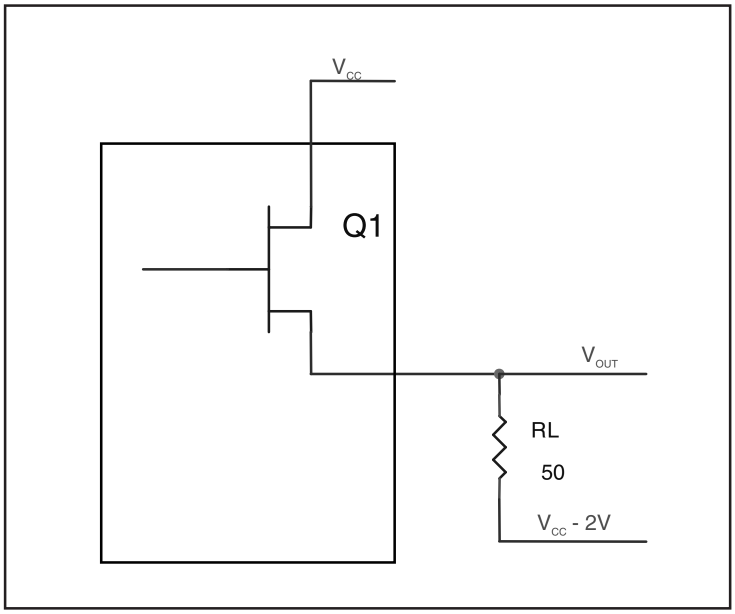


FIGURE 4. LVPECL DRIVER CIRCUIT AND TERMINATION

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of V_{CC} - 2V.

- For logic high, $V_{OUT} = V_{OH\_MAX} = \mathbf{V_{CC\_MAX} - 0.9V}$

  $(V_{CC\_MAX} - V_{OH\_MAX}) = \mathbf{1.0V}$

- For logic low, $V_{OUT} = V_{OL\_MAX} = \mathbf{V_{CC\_MAX} - 1.7V}$

  $(V_{CC\_MAX} - V_{OL\_MAX}) = \mathbf{1.7V}$

Pd_H is power dissipation when the output drives high.
Pd_L is the power dissipation when the output drives low.

$Pd\_H = [(V_{OH\_MAX} - (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OH\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) =$
$[(2V - 0.9V)/50\Omega] * 0.9V = \mathbf{19.8mW}$

$Pd\_L = [(V_{OL\_MAX} - (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OL\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) =$
$[(2V - 1.7V)/50\Omega] * 1.7V = \mathbf{10.2mW}$

Total Power Dissipation per output pair = Pd_H + Pd_L = **30mW**

Reliability Information

Table 7A. θ_{JA} vs. Air Flow Table for 20 Lead TSSOP

θ_{JA} by Velocity (Meters per Second)			
	0	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	91.1°C/W	86.7°C/W	84.6°C/W

Table 7B. θ_{JA} vs. Air Flow Table for 20 Lead VFQFN

θ_{JA} by Velocity (Meters per Second)			
	0	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	57.5°C/W	50.3°C/W	45.1°C/W

Transistor Count

The transistor count for ICS8535BI-01 is: 412

PACKAGE OUTLINE - G SUFFIX FOR 20 LEAD TSSOP

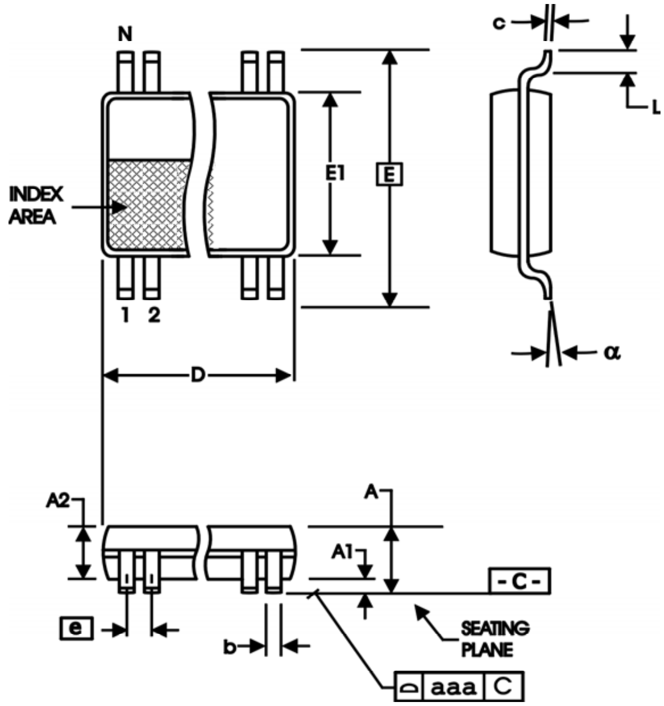
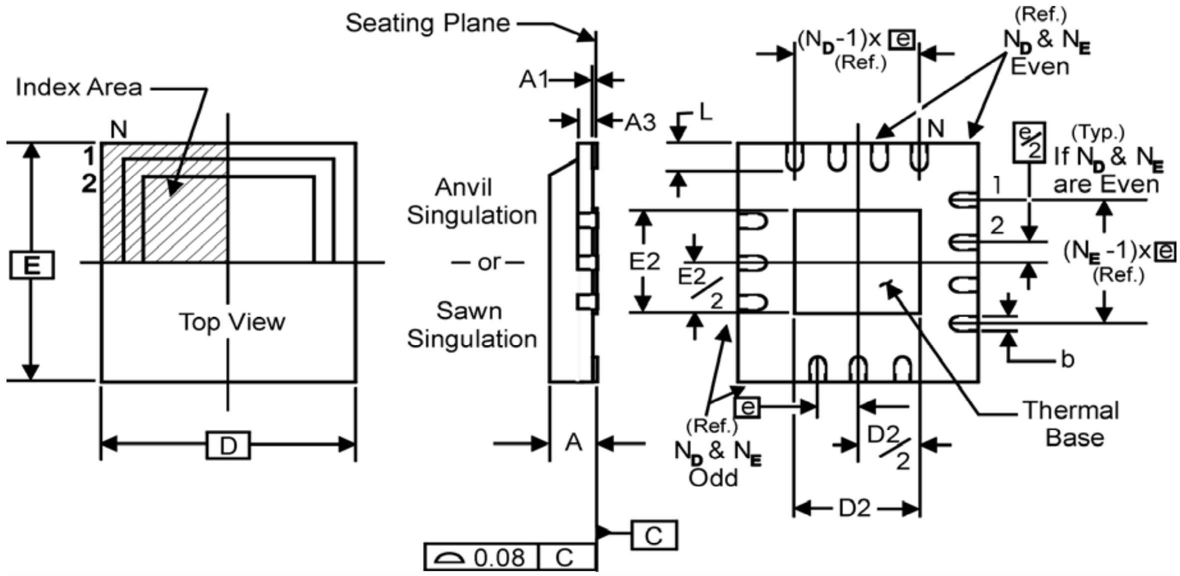


TABLE 8A. PACKAGE DIMENSIONS FOR TSSOP

SYMBOL	Millimeters	
	Minimum	Maximum
N	20	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
α	0°	8°
aaa	--	0.10

REFERENCE DOCUMENT: JEDEC PUBLICATION 95, MO-153

Package Outline - K Suffix for 20 Lead VFQFN



NOTE: The following package mechanical drawing is a generic drawing that applies to any pin count VFQFN package. This drawing is not intended to convey the actual pin count or pin layout of this device. The pin count and pinout are shown on the front page. The package dimensions are in Table 8 below.

Table 8B. Package Dimensions for 20 Lead VFQFN

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS		
SYMBOL	MINIMUM	MAXIMUM
N	20	
A	0.80	1.0
A1	0	0.05
A3	0.25 Reference	
b	0.18	0.30
e	0.50 BASIC	
N_D	5	
N_E	5	
D	4.0	
D2	0.75	2.80
E	4.0	
E2	0.75	2.80
L	0.35	0.75

Reference Document: JEDEC Publication 95, MO-220

TABLE 9. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS8535BGI-01	ICS8535BGI01	20 Lead TSSOP	tube	-40°C to 85°C
ICS8535BGI-01T	ICS8535BGI01	20 Lead TSSOP	2500 tape & reel	-40°C to 85°C
ICS8535BGI-01LF	ICS8535BI01L	20 Lead "Lead Free" TSSOP	tube	-40°C to 85°C
ICS8535BGI-01LFT	ICS8535BI01L	20 Lead "Lead Free" TSSOP	2500 tape & reel	-40°C to 85°C
ICS8535BKI-01	35BI01	20 Lead VFQFN	tube	-40°C to 85°C
ICS8535BKI-01T	35BI01	20 Lead VFQFN	2500 tape & reel	-40°C to 85°C
ICS8535BKI-01LF	5BI01L	20 Lead "Lead-Free" VFQFN	tube	-40°C to 85°C
ICS8535BKI-01LFT	5BI01L	20 Lead "Lead-Free" VFQFN	2500 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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